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at least one optical measuring device disposed adjacent to an outer peripheral portion of said polishing table and below said polishing surface of said polishing table, said at least one optical measuring device being operable to measure a thickness of a layer formed on the surface of the substrate; and

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at least one notch formed in said outer peripheral portion of said polishing table, said at least one notch allowing light emitted from said at least one optical measuring device to pass therethrough and be incident on the surface of the substrate and allowing light reflected from the surface of the substrate to pass therethrough and be incident on said at least one optical measuring device, wherein said top ring is swingable between an inner area and an outer area on said polishing table so that the light emitted from said at least one optical measuring device is incident on a position ranging from an outer circumferential edge to a central portion of the substrate.

2. (Amended) A polishing apparatus according to claim 1, wherein the substrate has a semiconductor device thereon.

4. (Amended) A polishing apparatus according to claim 1, wherein when said top ring is swung to a maximum, an area of the substrate which projects outward beyond an outer circumferential edge of said polishing table is not more than 40% of an entire area of the surface of the substrate being polished.

5. (Amended) A polishing apparatus according to claim 1, further comprising a nozzle operable to supply a cleaning liquid to said at least one optical measuring device.